L Number			DP	THE STATE OF THE S
+	219	91 ((device or chip or die) with (made))	DB d USPAT;	Time stamp
1	1	((test or burn) with substrate)	US-PGPUB;	2002/08/28 12:5
			EPO; JPO;	
			DERWENT;	
2		2 (((device or chip or dia)	IBM TDB	
			USPAT;	2002/08/28 10:2
		and ((test or burn) with substrate)) and (stabilizer or standoff)	US-PGPUB;	2002/08/28 10:2
		(Stabilizer of Standoff)	EPO; JPO;	
			DERWENT;	
3	9	2 ((((device or chip or die) with (pad\$2))	IBM_TDB	
		and (lest of plinn) with substant	USPAT;	2002/08/28 11:4:
	1	(bcdbilizer of Standoff) and	US-PGPUB;	
		(@ad<200006008)	EPO; JPO;	
4			DERWENT; IBM TDB	
4		(((device or chip or die) with (pad\$2))	USPAT;	2000 (00 (00
		and (test of bilen) with substrate()	US-PGPUB;	2002/08/28 11:00
		\\Scap_iiia	EPO; JPO;	
		or insulat\$4 or photopolymer))	DERWENT;	
5	1415	J	IBM TDB	
	1410		USPAT;	2002/08/28 10:42
		or insulat\$4 or photopolymer))	US-PGPUB;	2002/00/28 10:42
	1		EPO; JPO;	
			DERWENT;	
õ	169	(((stabilizer or otandess	IBM TDB	
		- \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	USPAT;	2002/08/28 10:40
		or insulat\$4 or photopolymer))) and ((test or burn) and (chip or die or device))	US-PGPUB;	1 100,20 10.40
į		(chip of die or device))	EPO; JPO;	
			DERWENT;	
'	169	((((stabilizer or standoff) with	IBM_TDB	
1		(dielctric or insulat\$4 or photopolymer)))	USPĀT;	2002/08/28 10:43
1		I wild ((Cest Of Dilrn) and (chin on all	US-PGPUB;	
		device))) and (@ad<200006008)	EPO; JPO;	
			DERWENT;	
1	406967	((test or burn or KGD) and (IC or chip or	IBM_TDB	
		die or device))	USPAT;	2002/08/28 10:41
ĺ			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	370	(((test or burn or KGD) and (IC or chip or	IBM_TDB USPAT:	2222 (22 (22
		Gic Or Gevice) and (/(gfahiligam a	US-PGPUB;	2002/08/28 10:42
1		Standoll Same (dielectric on incline	EPO; JPO;	
		photopolymer)))	DERWENT;	
	370	////	IBM TDB	
	3/0	((((test or burn or KGD) and (IC or chip	USPAT;	2002/08/28 10:51
		or are or device))) and (((e+ahili	US-PGPUB;	
			EPO; JPO;	
1		photopolymer)))) and (@ad<200006008)	DERWENT;]
	2175	(((device or chin and dis)	IBM TDB	
	21/3	(((device or chip or die) with (pad\$2))	USPAT;	2002/08/28 11:03
İ		and ((test or burn) with substrate)) and ((@ad<200006008)	US-PGPUB;	0, -0
			EPO; JPO;	
			DERWENT;	
ĺ	185	324/\$.ccls. and standoff	IBM_TDB	
			USPAT;	2002/08/28 10:54
	1		US-PGPUB;	
	1		EPO; JPO;	
	ļ		DERWENT;	
	10		IBM_TDB	
1		Dhotopolymer)	USPAT;	2002/08/28 11:00
		_	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0	((Scapilizer or standoff) with	IBM TDB	
	!]	photopolymer)) and ((device or chi-	USPAT;	2002/08/28 11:02
	1 3		US-PGPUB;	
		1 -	EPO; JPO;	
			DERWENT; IBM TDB	
			בויוי ועוא ז	

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15	722	and ((test or burn) with substrate)) and	USPAT; US-PGPUB;	2002/08/28 11:09
		(@ad<200006008)) and (dielectric or photpolymer)	EPO; JPO; DERWENT; IBM TDB	
17	724	((((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and (@ad<200006008)) and (dielectric or photopolymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/28 11:35
18	12		IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/28 11:39
19	542		DERWENT; IBM_TDB USPAT; US-PGPUB;	2002/08/28 11:39
20	0	324/728.ccls.	EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/00/00 11 20
		324/720.0018.	US-PGPUB; EPO; JPO; DERWENT;	2002/08/28 11:39
22	2902	324/765.ccls.	IBM TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/28 11:39
21	93	324/528.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/28 11:40
23	838	257/48.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/28 11:42
24	830	257/48.ccls. and (@ad<200006008)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/28 11:43
25	742	257/48.ccls. and (@ad<20000608)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/28 12:01
26	120	(((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and balance	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/28 12:01
27	104	((((device or chip or die) with (pad\$2)) and ((test or burn) with substrate)) and balance) and (@ad<20000608)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/28 12:21
28	0	(dielectric near standoff) and ((chip or die) with (test or burn))	DERWENT; IBM_TDB USPAT; US-PGPUB;	2002/08/28 12:07
29	1	(dielectric with standoff) and ((chip or die) with (test or burn))	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2002/08/28 12:18
			EPO; JPO; DERWENT; IBM_TDB	

30	1.650	057/770		
30	1650	257/773.ccls.	USPAT;	2002/08/28 12:20
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
31	1403	257/773.ccls. and (@ad<20000608)	USPAT;	2002/08/28 12:43
			US-PGPUB;	2002/08/28 12:43
			EPO; JPO;	
		·	DERWENT;	
32	434	/257/772 1 /0 1 /000000000	IBM_TDB	
32	434	(257/773.ccls. and (@ad<20000608)) and pad	USPAT;	2002/08/28 12:38
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
33	1		USPAT	2002/08/28 12:25
34	8	(tability is the state (tad (tad (20000000))) and	USPAT;	2002/08/28 12:38
		standoff	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
35	63	((device or chip or die) with balance) and	IBM_TDB	0000400400
		((test or burn) with substrate)	USPAT; US-PGPUB;	2002/08/28 12:42
		The same of the sa	EPO; JPO;	
			DERWENT;	
			IBM TDB	
36	2287	((device or chip or die) with (stable or	USPAT;	2002/08/28 12:43
		collapse)) and (test or burn) and	US-PGPUB;	
		substrate	EPO; JPO;	
			DERWENT;	-
37	1939	(((device or chip or die) with (stable or	IBM_TDB USPAT;	2000/00/00 10 45
		collapse)) and (test or burn) and	US-PGPUB;	2002/08/28 12:45
		substrate) and (@ad<20000608)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
38	0	standoff adj is	USPĀT;	2002/08/28 12:44
			US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	
40	168	standoff with (enhance or increase or	IBM_TDB USPAT;	2002/08/28 12:49
		benefit)	US-PGPUB;	2002/00/20 12.49
			EPO; JPO;	
			DERWENT;	
41	153	(-t	IBM_TDB	
1 41	153	(standoff with (enhance or increase or benefit)) and (@ad<2000608)	USPAT;	2002/08/28 13:06
		benefic), and (@ad<20000608)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
42	43	standoff with (stabl\$5 or balance)	USPAT;	2002/08/28 13:03
		,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
43	3010	(((device or chip or die) with pad\$2) same	IBM TDB	0000/00/00 15 55
1	2010	(test or burn)) and substrate	USPAT;	2002/08/28 13:00
		(cool of Marily) and Subscrate	US-PGPUB; EPO; JPO;	
		•	DERWENT;	
			IBM TDB	
44	0	((((device or chip or die) with pad\$2)	USPAT;	2002/08/28 13:13
		same (test or burn)) and substrate) and	US-PGPUB;	
		(standoff with (stabl\$5 or balance))	EPO; JPO;	
			DERWENT;	
45	586	((((device or chip or die) with pad\$2)	IBM_TDB	2002/00/20 12:04
-	300	same (test or burn)) and substrate)	USPAT; US-PGPUB;	2002/08/28 13:04
		and(stabl\$5 or balance)	EPO; JPO;	
		/	DERWENT;	
			IBM TDB	

46	161	((((device or chip or die) with pad\$2)		
		same (test or burn)) and substrate) and	USPAT;	2002/08/28 13:04
		((stabl\$5 or balance) with (chip or die or	US-PGPUB;	
		device))	EPO; JPO;	
		40.200,7	DERWENT;	
47	136	((((device or chip or die) with pad\$2)	IBM_TDB	
		same (test or burn)) and substrate) and	USPAT;	2002/08/28 13:14
		((stabl\$5 or balance) with (chip or die or	US-PGPUB;	
		device))) and (@ad<20000608)	EPO; JPO;	
		(64412000000)	DERWENT;	
49	67	((((device or chip or die) with pad\$2)	IBM_TDB	
		same (test or burn)) and substrate) and	USPAT;	2002/08/28 13:17
		((chip or die) with (stabl\$5 or balance))	US-PGPUB;	
		(Scabios of Dalance))	EPO; JPO;	
			DERWENT;	
50	55	((((device or chip or die) with pad\$2)	IBM_TDB	
		same (test or burn)) and substrate) and	USPAT;	2002/08/28 13:19
		((chip or die) with (stabl\$5 or balance)))	US-PGPUB;	
		and (@ad<20000608)	EPO; JPO;	
		, , , , , , , , , , , , , , , , , , , ,	DERWENT;	
51	319	((((device or chip or die) with pad\$2)	IBM TDB	
		same (test or burn)) and substrate) and	USPAT;	2002/08/28 13:18
		((chip or die) with (fall\$3 or bend\$3 or	US-PGPUB;	
		crack\$3))	EPO; JPO;	
		· · ·	DERWENT;	
52	254	((((device or chip or die) with pad\$2)	IBM_TDB	
		same (test or burn)) and substrate) and	USPAT;	2002/08/28 13:19
		((chip or die) with (fall\$3 or bend\$3 or	US-PGPUB;	
		crack\$3))) and (@ad<20000608)	EPO; JPO;	
		(644.200000)	DERWENT;	
			IBM TDB	